

08-18-2003



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of Conveying Party(ies): 8-8-03 (1) HIDEHARU YAHATA, (2) MASASHI HORIGUCHI, (3) YOSHIKAZU SAITOH AND (4) YASUSHI KAWASE		2. Name and Address of Receiving Party(ies): (1) Name: Hitachi, Ltd. Address: 6, Kanda Surugadai 4-chome Chiyoda-ku, Tokyo, Japan and (2) Name: Hitachi Device Engineering Co., Ltd Address: 3681, Hayano, Mobara-shi Chiba-ken, Japan 297-8581	
3. Nature of Conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other: Execution Dates: (1) March 25, 2002; (2) March 13, 2002; and (3)(4) March 14, 2002		4. (b) Patent Numbers:	
4. (a) Patent Application Number(s): 10636558 If this document is being filed together with a new application, the execution date of the application is: <input type="checkbox"/> Additional Numbers Attached.			
5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed: Name: Stanley P. Fisher Address: Reed Smith LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, VA 22042		6. Total Number of Applications and Patents Involved: 1 7. Total Fee: \$40.00 (37 C.F.R. § 3.41) <input checked="" type="checkbox"/> Enclosed. <input checked="" type="checkbox"/> Authorized to be charged to deposit account. 8. Deposit Account Number: 08-1480 <small>ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT</small>	
DO NOT USE THIS SPACE			
9. Statement and Signature: <i>To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.</i> <div style="display: flex; justify-content: space-between;"><div>Stanley P. Fisher, Registration No. 24, 344</div><div> August 8, 2003 Juan Carlos A. Marquez, Registration No. 34,072</div></div> Total number of pages comprising cover sheet: 1			

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ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD. and Hitachi Device Engineering Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3681, Hayano, Mobara-shi, Chiba, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and Hitachi Device Engineering Co., Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR MEMORY DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and Hitachi Device Engineering Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and Hitachi Device Engineering Co., Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1)	<u>Hideharu Yahata</u>	<u>(Hideharu YAHATA)</u>	<u>25 / March / 2002</u>
2)	<u>Masashi Horiguchi</u>	<u>(Masashi HORIGUCHI)</u>	<u>13 / March / 2002</u>
3)	<u>Yoshikazu Saitoh</u>	<u>(Yoshikazu SAITOH)</u>	<u>14 / March / 2002</u>
4)	<u>Yasushi Kawase</u>	<u>(Yasushi KAWASE)</u>	<u>14 / March / 2002</u>
5)	_____	_____	_____
6)	_____	_____	_____
7)	_____	_____	_____
8)	_____	_____	_____
9)	_____	_____	_____
10)	_____	_____	_____